

This Page Is Inserted by IFW Operations  
and is not a part of the Official Record

## **BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning documents *will not* correct images,  
please do not report the images to the  
Image Problem Mailbox.**

**WIRE-BONDED PACKAGE WITH ELECTRICALLY INSULATING  
WIRE ENCAPSULANT AND THERMALLY CONDUCTIVE  
OVERMOLD**

**ABSTRACT OF THE DISCLOSURE**

The specification discloses an apparatus comprising a die mounted on a substrate, the die being connected to the substrate by a plurality of wires, and a mold cap encapsulating the die and the plurality of wires, the mold cap comprising an electrically insulating portion encapsulating the wires and at least a portion of the die and a thermally conductive portion overmolded on the die and the electrically insulating portion. Also disclosed is a process comprising providing a die connected to a substrate by a plurality of wires, encapsulating the wires and at least a portion of the die in an electrically insulating material, and encapsulating the die, the wires and the electrically insulating material in a thermally conductive material. Other embodiments are disclosed and claimed.